

ASSP for Audio

■ ICs for Audio Common Use (continued)

● ICs for Sound Output

Part No.	Operating Range (V)	Absolute Max. Ratings (V)	Output				Functions						Package		No.		
			ch	Type	R _L (Ω)	P _O (W)	Gain (dB)	STB	Mute	Vol	Tone	CR Built-in					
AN7585	10 to 32	35	3		8 4	10 W × 2 19 W × 1	34	○						HZIP023-P-0138A	—		
AN7582			2		8	10 W × 2		○						○	○	HSIP012-P-0000E	B23
AN7583			3		8 4	10 W × 2 19 W × 1										HSIP012-P-0000D	B22
AN17800A	9 to 22	25	1		8	2 W	28	○						HZIP012-P-0700	—		
AN17801A																	
AN17802A	9 to 24	27															

○BTL specification No mark: OTL specification

● Portable Stereo Headphone Amplifier

Part No.	Operating Voltage (V)	Process	Functions	Package	
					No.
AN17020A	2 to 3.5/ 0.9 to 3.5	Bipolar	Headphone amplifier, Line amplifier	QFN016-P-0304A	B143
AN17880A	1.8 to 4.5		Headphone amplifier (center Amp system)	SSOP024-P-0300D	B82
AN7504SB	0.98 to 2		Headphone amplifier, Bus boost, Tape selector, Tape preamplifier, Stand-by mute	SSOP028-P-0375E	B91

● Notebook-sized PC Single-chip Voice Signal Processing Circuits

Part No.	Operating Voltage (V)	Process	Functions	Package	
					No.
AN7515SH	3.3 to 6	Bipolar	Stand-by of line amplifier, headphone amplifier and speaker amplifier and mute switch are incorporated	HSOP056-P-0300	B106
AN17000A	4.5 to 5.5		On-chip speaker amplifier circuit, headphone amplifier circuit, line amplifier circuit, volume and bus boost circuit		
AN12940AA	5		Speaker amplifier 2-ch, AGC	HSOP056-P-0300A	B107
AN12941A					
▲ AN12942B			Speaker amplifier 2-ch, Line amplifier 2-ch, Headphone amplifier 2-ch, AGC	HQFP048-P-0707	B112
AN12944A					

▲: Under development

(Package Symbol) HQFP = Heat-sink Quad Flat Package, HSIP = Heat-sink Single-In-line Plastic Package, HSOP = Heat-sink Small Outline Package, HZIP = Heat-sink Zigzag-In-line Plastic Package, QFN = Quad Flat Nonleaded Package, SSOP = Shrink Small Outline Package